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Address	Tecnisco Ltd. 2-2-15 Minamishinagawa Shinagawaku 1400004 Tokyo
Country	Japan

PRODUCTS OR MACHINERY

Supplier of Cutting technology for technical glass, Grinding techniques for flat glass, Grinding techniques for straight edges, Grinding techniques for patterned glass, Matting / Supercalendering / etching / sand blasting technologies, Glassfrosting, Polishing technology, Mirror coating products, Bonding technology

We are a leading supplier of customized products that are manufactured by our advanced high-precision processes and composite technology. Our main products are glass parts for the MEMS industry and metal-heatsinks for opt-telecom and high power lasers.

After great efforts, we have succeeded in developing unique drilling processing to produce through holes and patterned micro-grooves. In particular, our structured glass wafers by drilling, sandblasting and Ultrasonic machining have become integrated into pressure, accelerometer and gyro sensor in the fields of automobile, measuring equipment and medical instruments.

We handle Pyrex, Eagle2000, Borofloat, SD2, SD3, SWYY, Quartz and Si. The features and benefits of our processing are Aspect ratio 3:1, Microthrough-hole $\phi 0.15\text{mm}$ and Accurate positioning and tolerance.

Glass products

We provide a variety of products from glass wafers for MEMS devices used in projectors or pressure/acceleration sensors to microfluidic glass products for the biotechnology/medical industries based on the customers' need. In addition, we have started providing processing of chemically-strengthened glasses for the touch panel industry. Glass products

Through glass via (TGV)

Most suitable for miniaturizing semiconductor devices. The metal via can improve the high-frequency properties of the devices

Micro-hole glass

Leads to the miniaturization of devices in combination with semiconductors/electronic parts

Cavity glass / Cap glass

Hi-precision cavity can be formed inside of the glass wafer. Transparent and thinner finish is available on the cavity bottom

Mesh glass

Can be used as general-purpose via wafers with the holes plated to form electrodes. Also suitable for cell-culture systems.

Spacer glass

Suitable for multilayer packaging by combining with semiconductor wafers such as MEMS devices.

Microfluidic glass

Microfluidic glass products with excellent thermal and chemical resistance. The microfluidic channels can be flexibly designed in 3 dimensions.

Company Profile of **Tecnisco Ltd.**

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